

Technical Data Sheet

FeedBond® EP-6000-SH5

Silicone Type Die Attach Adhesive

Description:

FeedBond®EP-6000-SH5 one-component, thermally curable, addition-curing silicone adhesive is developed for optoelectronic packaging application.

application. This adhesive can be used for LED chip and can be applied to automatic equipment.

Application Package:

Adhesive optoelectronic packaging application

Characteristics:

- No yellowing due to heat and light
- Middle viscosity that is adaptable to conventional processing methods such as pin transfer and dispensing.

UNCURED PROPERTIES		TEST DESCRIPTION	TEST METHOD
Appearance	Translucent liquid	Visual	FT-P006
Viscosity @ 25°C	10000±2000cps	Brookfield DV-III/CP-51 @ 5rpm	
Thixotropic Index @ 25°C	2.0±0.5	Brookfield DV-III/CP-51 Visc. @ 0.5rpm/Visc. @ 5rpm	FT-P008
Grind	< 10µm	Grind meter	FT-P026
Work Life @ 25°C	48hrs	25% increase in visc. @ 5rpm	FT-P024
Shelf Life@ 0~10°C	6months		FT-P018
CURE CONDITION		TEST DESCRIPTION	TEST METHOD
Standard Cure Condition		120 minutes in oven @150°C	

These figures are only intended as a guide and should not be used in preparing specifications.

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PHYSIOCHEMICAL PROPERTIES	TEST DESCRIPTION	TEST METHOD
Hardness Shore D 52±5	Durometer Shore D	FT-P037
Linear CTE 213ppm/°C	TMA Expansion Mode(25~150°C)	FT-M016
Dynamic Tensile Modulus @25°C 181 Mpa @150°C 84 Mpa @250°C 71 MPa	Dynamic Mechanical Thermal Analysis using <1.6 mm thick specimen	FT-M019
Light Transmissivity after curing 89%	450nm /1mm thickness	FT-P038
Yellow Index 2.4	450nm /1mm thickness	FT-P043
MECHANICAL PROPERTIES-POST CURE	TEST DESCRIPTION	TEST METHOD
Die Shear Strength @ 25°C 1.4 Kg/die	45mil × 45mil die on Ag Leadframe	FT-M012
Die Shear Strength @ 160°C 900 g/die	45mil × 45mil die on Ag Leadframe	FT-M012
Die Shear Strength @ 260°C 700g/die	45mil × 45mil die on Ag Leadframe	FT-M012

Instruction

All surfaces must be clean and free of contaminants that will inhibit the cure of EP-6000-SH5.

Examples of inhibiting contaminants are sulfur containing materials, plasticizers, urethanes, amine containing materials and organometallic compounds – especially organotin compounds.

If a substrate's ability to inhibit cure is unknown, a small scale test should be run to determine compatibility.

Thawing

Place the container to stand vertically for 20mins.**DO NOT** open the container before adhesive reaches ambient temperature to prevent the moisture condensation. Any moisture that collects on the thawed container should be removed prior to use. Adhesives that appear to have separated should not be used.

Storage

Adhesive should be stored @ 0~10°C. The shelf life of the material is only valid when the material has been stored at the correct storage condition.

Availability

FeedBond® adhesives are packaged in syringes or pots per customer specification. For the details, please contact our Customer Service or sales department.